

8channels Tx TGV Photoelectric Interposer Chip

Product Introduction

The 8channels Tx TGV optoelectronic interposer chip uses laser induction and deep silicon etching to achieve glass-based signal switching, and uses the redistribution layer (RDL) and micro-bump process to achieve a wiring bandwidth of more than 110GHz, significantly improving signal transmission efficiency and density; matching the mainstream eight-channel silicon photonic modulation chip and electric driver chip to achieve an 8-channel standardized solution, while being compatible with the pin definitions of mainstream silicon photonic chips and electric chips, achieving a high degree of integration of optoelectronic hybrid packaging; laser direct writing optical waveguides and interposer internal slots can be integrated on the chip to achieve low-loss and high-density optical path fan-in and fan-out.

Performance Features

- 8-inch wafer-level TGV MPW tape-out
- RDL and micro-bump process, wiring bandwidth exceeds 110GHz
- Support optoelectronic chip flipchip packaging
- Support low-loss optical waveguide laser direct writing
- Support three-dimensional structure slotting, support low-loss optical coupling

Key parameter indicators:

Parameters	Scope
Interposer chip size	10mm×9mm
Interposer glass thickness	265μm
Wiring bandwidth	> 110GHz
TGV hole opening	60μm—25μm
RDL line width and spacing	80μm/15μm
RDL thickness	3μm
PI thickness	5μm
Bump ball diameter	60μm

Addr: Rm. 1202, Building 1, D&J Innovation Park, Nanwan Street, Longgang District, Shenzhen City, Guangdong Province

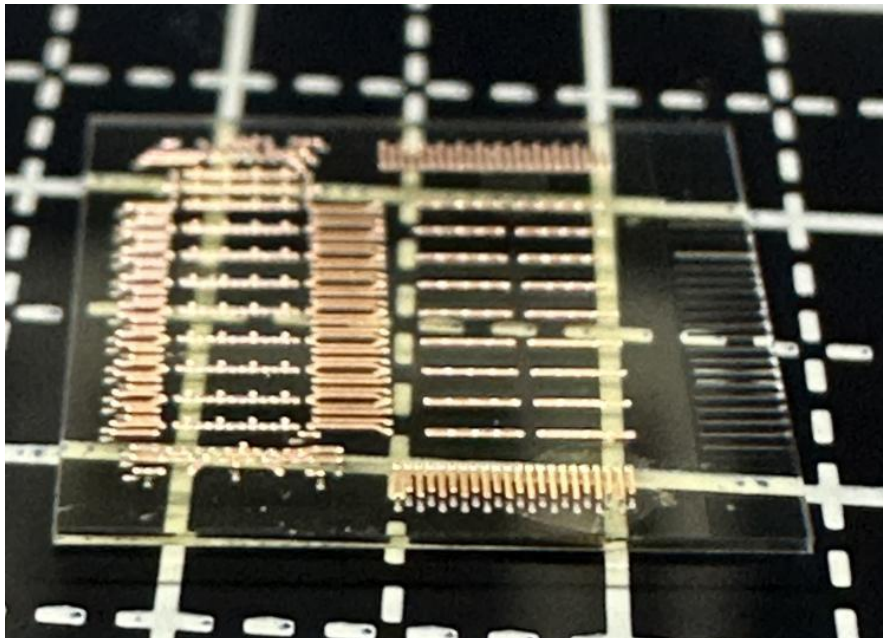
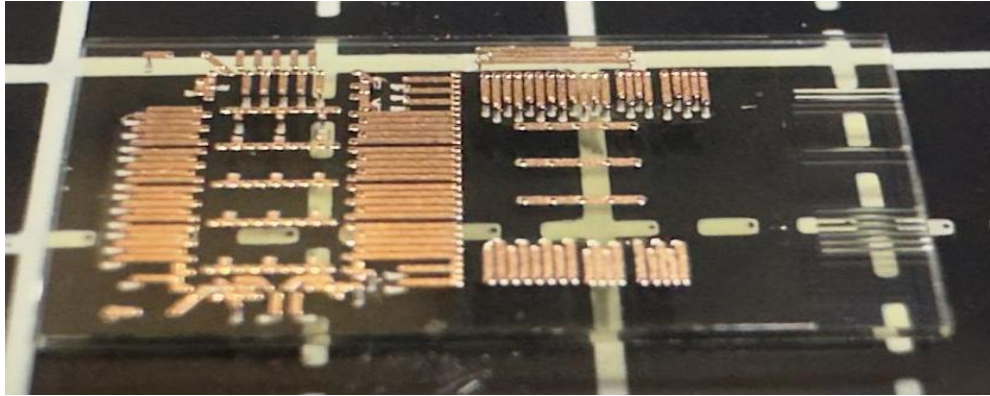
Tel: +86-755-84652252

Moblle: +86-189 4877 6698

Email: info@photonicsv.com

URL: <https://www.photonicsv.com>

TGV chip application diagram:



Addr: Rm. 1202, Building 1, D&J Innovation Park, Nanwan Street, Longgang District, Shenzhen City, Guangdong Province

Tel: +86-755-84652252

Email: info@photonicsv.com

Moblle: +86-189 4877 6698

URL: <https://www.photonicsv.com>